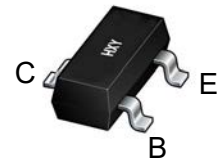




Features

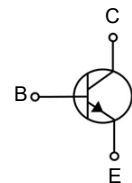
- Collector Current: $I_C=0.5A$
- Power Dissipation of 300mw



Package Marking and Ordering Information

Product ID	Pack	Qty(PCS)
BC817-16/25/40	SOT-23	3000

SOT-23



Maxmim Ratings (Ta=25 unless otherwise noted)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V_{CBO}	50	V
Collector-Emitter Voltage	V_{CEO}	45	V
Emitter-Base Voltage	V_{EBO}	5	V
Collector Current	I_C	500	mA
Collector Power Dissipation	P_C	300	mW
Thermal Resistance From Junction To Ambient	$R_{\theta JA}$	417	°C/W
Junction Temperature	T_j	150	°C
Storage Temperature	T_{stg}	-55~+150	°C

Classifiction Of h_{FE}

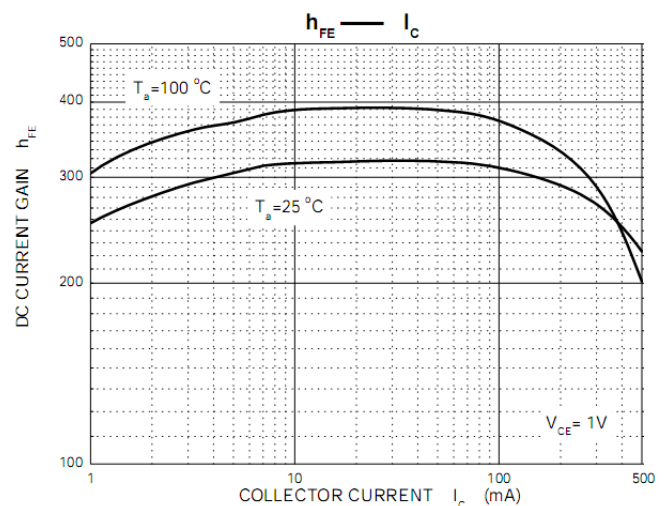
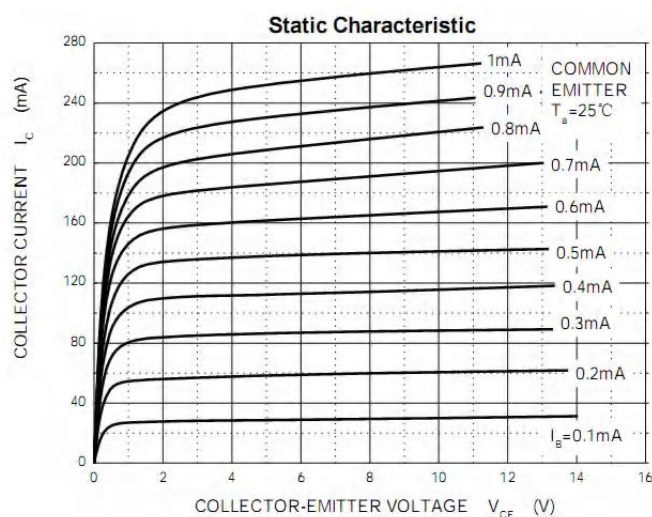
Rank	BC817-16	BC817-25	BC817-40
Range	100-250	160-400	250-600
Marking	6A	6B	6C

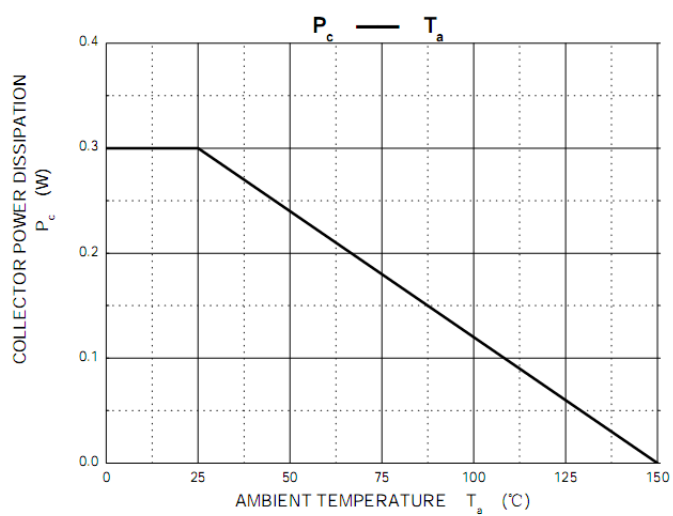
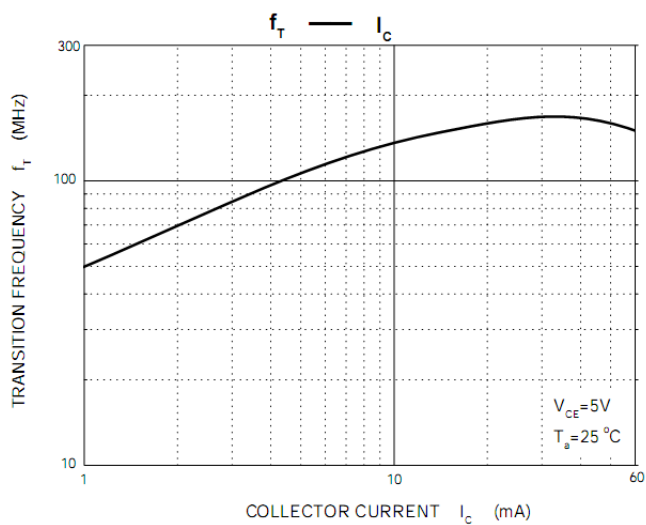
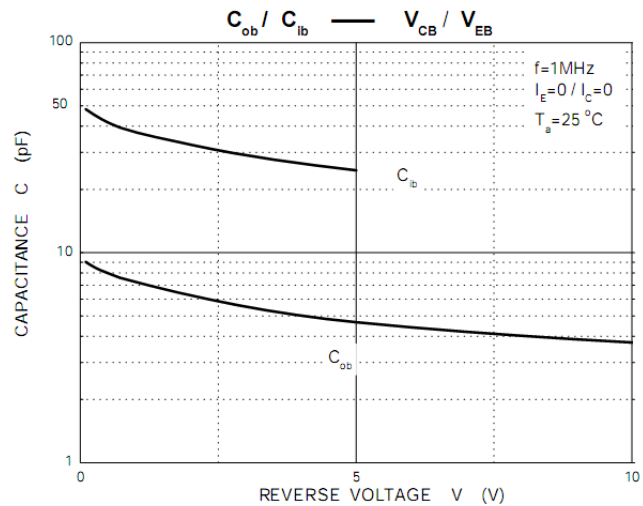
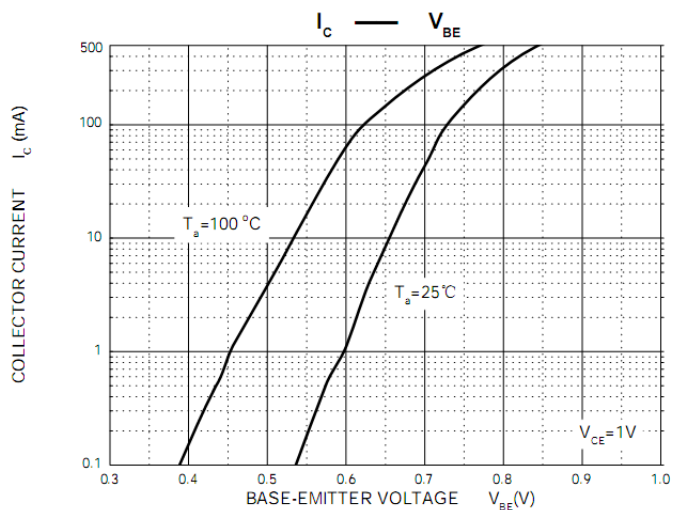
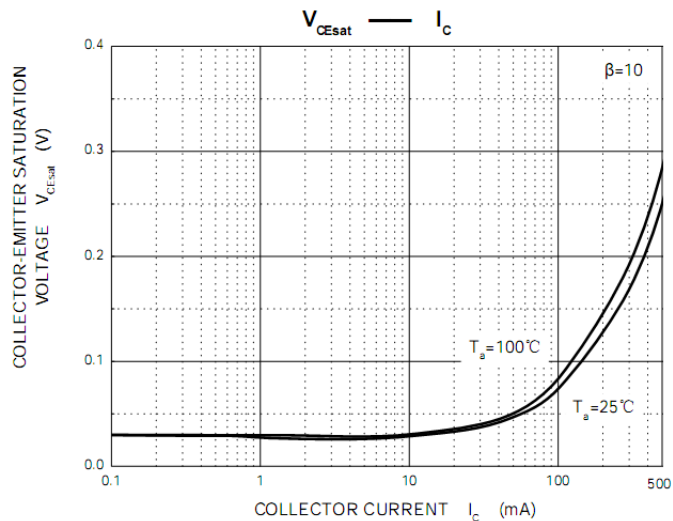
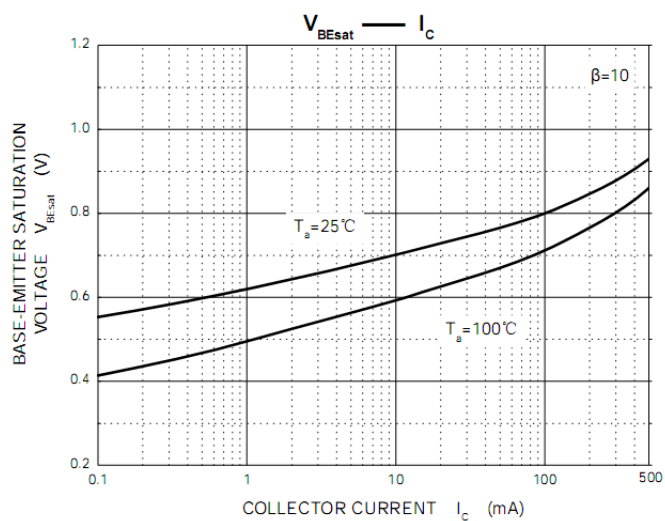


Electrcal Charcteristics ($T_a=25$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V_{CBO}	$I_C = 10\mu A, I_E = 0$	50			V
Collector-emitter breakdown voltage	V_{CEO}	$I_C = 10mA, I_B = 0$	45			V
Emitter-base breakdown voltage	V_{EBO}	$I_E = 1\mu A, I_C = 0$	5			V
Collector cut-off current	I_{CBO}	$V_{CB} = 45V, I_E = 0$			0.1	μA
Emitter cut-off current	I_{EBO}	$V_{EB} = 4V, I_C = 0$			0.1	μA
DC current gain	$h_{FE(1)}$	$V_{CE} = 1V, I_C = 100mA$	100		600	
	$h_{FE(2)}$	$V_{CE} = 1V, I_C = 500mA$	40			
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 500mA, I_B = 50mA$			0.7	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = 500mA, I_B = 50mA$			1.2	V
Base-emitter voltage	V_{BE}	$V_{CE} = 1V, I_C = 500mA$			1.2	V
Collector capactiance	C_{ob}	$V_{CB} = 10V, f = 1MHz$		10		pF
Transition frequency	f_T	$V_{CE} = 5V, I_C = 10mA$ $f = 100MHz$	100			MHz

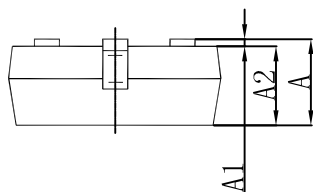
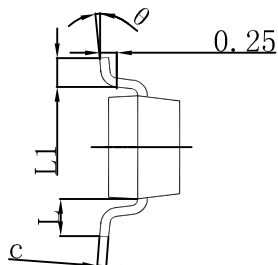
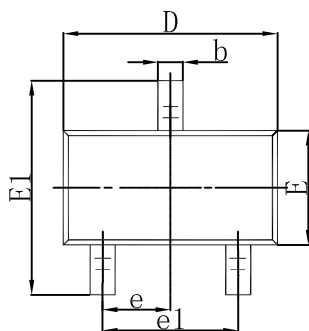
Typical Characteristics





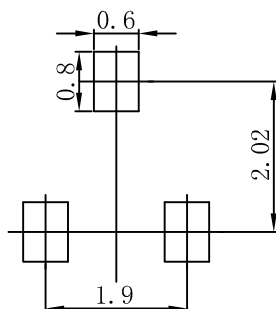


SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:
1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.



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